NOTICE OF REVISION (NOR) (See MIL-STD-480 for instructions) This revision described below has been authorized for the document listed.	DATE (YYMMDD) 92-10-05	Form Approved OMB No. 0704-0188

1. ORIGINATOR NAME AND ADDRESS	2. CAGE CODE	3. NOR NO.
Defense Electronics Supply Center Dayton, Ohio 45444-5270	67268	5962-R337-92
	4. CAGE CODE 67268	5. DOCUMENT NO. 84141
6. TITLE OF DOCUMENT MICROCIRCUIT, DIGITAL, BIPOLAR, ADVANCED LOW-POWER SCHOTTKY TTL, MULTIPLEXER, MONOLITHIC SILICON	7. REVISION LETTER C	D
	8. ECP NO. 84141ECP-1	

9. CONFIGURATION ITEM (OR SYSTEM) TO WHICH ECP APPLIES

All

10. DESCRIPTION OF REVISION

Sheet 1: Revisions ltr column; add "D".
Revisions description column; add "Changes in accordance with NOR 5962-R337-92".
Revisions date column; add "92-10-05".
Revision level block; change from "B" to "D".
Rev status of sheets; for sheet 4, change from "B" to "D".

Sheet 4: Table I, output current, I_O; change minimum limit from "-30 mA" to "-20 mA".
Revision level block; change from "B" to "D".

11. THIS SECTION FOR GOVERNMENT USE ONLY

a. CHECK ONE

[X] EXISTING DOCUMENT SUPPLEMENTED BY THIS NOR MAY BE USED IN MANUFACTURE.

[ ] REVISED DOCUMENT MUST BE RECEIVED BEFORE MANUFACTURER MAY INCORPORATE THIS CHANGE.

[ ] CUSTODIAN OF MASTER DOCUMENT SHALL MAKE ABOVE REVISION AND FURNISH REVISED DOCUMENT TO:

b. ACTIVITY AUTHORIZED TO APPROVE CHANGE FOR GOVERNMENT	SIGNATURE AND TITLE	DATE (YYMMDD)
DESC-ECC	Monica L. Poelking Chief, Custom Microelectronics	92-10-05
12. ACTIVITY ACCOMPLISHING REVISION DESC-ECC	REVISION COMPLETED (Signature) Thanh V. Nguyen	DATE (YYMMDD) 92-10-05

NOTICE OF REVISION (NOR)

(See MIL-STD-480 for instructions)

This revision described below has been authorized for the document listed.

DATE (YYMMDD): 91-11-18

Form Approved OMB No. 0704-0188

1. ORIGINATOR NAME AND ADDRESS

Defense Electronics Supply Center
Dayton, Ohio 45444-5277

2. CAGE CODE: 67268

3. NOR NO.: 5962-R014-92

4. CAGE CODE: 67268

5. DOCUMENT NO.: 84141

6. TITLE OF DOCUMENT

MICROCIRCUIT, DIGITAL, ADVANCED LOW-POWER SCHOTTKY TTL, MULTIPLEXER, MONOLITHIC SILICON

7. REVISION LETTER: B (Current) / C (New)

8. ECP NO.

9. CONFIGURATION ITEM (OR SYSTEM) TO WHICH ECP APPLIES

All

10. DESCRIPTION OF REVISION

Sheet 1: Revisions ltr column; add "C".
Revisions description column; add "Changes in accordance with NOR 5962-R014-92".
Revisions date column; add "91-11-18".

Sheet 4: Table I, change TPHL1 from 8ns min TO 7ns min.
Sheet 5: Table I, change TPLH2 from 7ns min to 5ns min.

11. THIS SECTION FOR GOVERNMENT USE ONLY

a. CHECK ONE

[X] EXISTING DOCUMENT SUPPLEMENTED BY THIS NOR MAY BE USED IN AND MANUFACTURE.

[ ] REVISED DOCUMENT MUST BE RECEIVED BEFORE MANUFACTURER MAY INCORPORATE THIS CHANGE.

[ ] CUSTODIAN OF MASTER DOCUMENT SHALL MAKE ABOVE REVISION FURNISH REVISED DOCUMENT TO:

b. ACTIVITY AUTHORIZED TO APPROVECHANGE FOR GOVERNMENT	SIGNATURE AND TITLE	DATE (YYMMDD)
DESC-ECC	Monica L. Poelking Chief, Custom Microelectronics	91-11-18
12. ACTIVITY ACCOMPLISHING REVISION	REVISION COMPLETED (Signature)	DATE (YYMMDD)
DESC-ECC	Larry T. Gauder	91-11-18

REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
B	Table I, added footnotes and changed propagation delay times. Added Figure 4, switching waveforms and test circuit. Change to military drawing format. Editorial changes throughout.	88 MAY 03	M. A. Frye

REV																				
SHEET																				
REV																				
SHEET																				

REV STATUS OF SHEETS															
REV	B	B	B	B	B	B	B	B	B	B	B				
SHEET	1	2	3	4	5	6	7	8	9	10	11				

PMIC N/A

STANDARDIZED MILITARY DRAWING

THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE

AMSC N/A

PREPARED BY
Christopher A Rauch

CHECKED BY
David Johnson

APPROVED BY
Michael A. Frye

DRAWING APPROVAL DATE
02 JULY 1985

REVISION LEVEL
B

DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

MICROCIRCUIT, DIGITAL, ADVANCED LOW-POWER SCHOTTKY TTL, MULTIPLEXER, MONOLITHIC SILICON

SIZE	CAGE CODE	
A	67268	84141

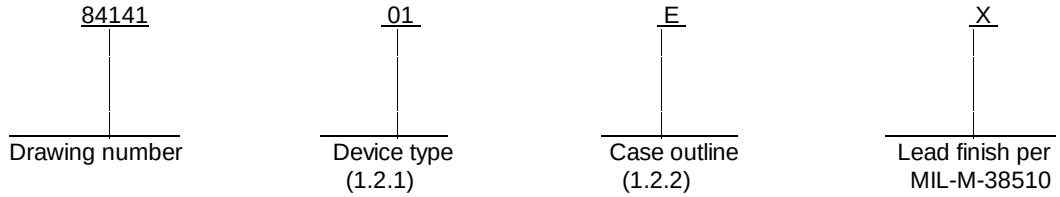
SHEET 1 OF 11

* US GOVERNMENT PRINTING OFFICE: 1987--748-129/60912

1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device types. The device type shall identify the circuit function as follows:

Device type	Generic number	Circuit
01	54ALS151	1 of 8 data selector/multiplexer

1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	Case outline
E	D-2 (16-lead, .840" x .310" x .200"), dual-in-line package
F	F-5 (16-lead, .440" x .285" x .085"), flat package package
2	C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package

1.3 Absolute maximum ratings.

Supply voltage range	-0.5 V dc minimum to +7.0 V dc maximum
Input voltage range	-1.5 V at -18 mA to +7.0 V
Storage temperature	-65°C to +150°C
Maximum power dissipation (P_D) per device	66.0 mW 1/
Lead temperature (soldering, 10 seconds)	+300°C
Thermal resistance, junction-to-case (θ_{JC})	See MIL-M-38510, appendix C
Junction temperature (T_J)	+175°C

1.4 Recommended operating conditions.

Supply voltage range	+4.5 V dc minimum to +5.5 V dc maximum
Minimum high level input voltage (V_{IH})	2.0 V dc
Maximum low level input voltage (V_{IL}):	
TC = +125°C	0.7 V dc
TC = -55°C	0.8 V dc
TC = +25°C	0.8 V dc
Case operating temperature range (T_C)	-55°C to +125°C

1/ Maximum power dissipation is defined as V_{CC} * I_{CC}, and must withstand the added P_D due to short circuit test; e.g., I_O.

2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth tables. The truth tables shall be as specified on figure 2.

3.2.3 Logic diagrams. The logic diagrams shall be as specified on figure 3.

3.2.4 Switching waveforms and test cirucit. The switching waveforms and test circuit shall be as specified on figure 4.

3.2.5 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.

3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

TABLE I. Electrical performance characteristics. 1/

Test	Symbol	Conditions $-55^{\circ}C \le T_C \le +125^{\circ}C$ Unless otherwise specified		Group A subgroups	Limits		Unit
					Min	Max	
High level output voltage	V_{OH}	V_{IH} = 2.0 V V_{CC} = 4.5 V I_{OH} = -0.4 mA 2/	VIL = 0.7 V	2	2.5		V
			VIL = 0.8 V	1,3			
Low level output voltage	V_{OL}	V_{IH} = 2.0 V V_{CC} = 4.5 V I_{OL} = 12.0 mA 2/	VIL = 0.7 V	2		0.4	V
			VIL = 0.8 V	1,3			
Input clamp voltage	V_{IC}	V_{CC} = 4.5 V I_{IN} = -18 mA		1, 2, 3		-1.5	V
High level input current	I_{IH1}	V_{CC} = 5.5 V V_{IN} = 2.7 V All other inputs = 0.0 V		1, 2, 3		20	μA
	I_{IH2}	V_{CC} = 5.5 V V_{IN} = 7.0 V All other inputs = 0.0 V		1, 2, 3		100	μA
Low level input current	I_{IL}	V_{CC} = 5.5 V V_{IN} = 0.4 V All other inputs = 4.5 V		1, 2, 3		-0.1	mA
Output current	I_O	V_{CC} = 5.5 V V_{OUT} = 2.25 V 3/		1, 2, 3	-30	-112	mA
Supply current	I_{CC}	V_{CC} = 5.5 V $V_{IN} \ge$ 4.5 V (All inputs)		1, 2, 3		12	mA
Functional tests		See 4.3.1c 4/		7, 8			
Propagation delay time, A, B, C to Y	tPLH1	V_{CC} = 4.5 V to 5.5 V C_L = 50 pF ±10% R_L = 500 Ω ±5% 5/ See figure 4		9, 10, 11	4	18.5	ns
	tPHL1			9, 10, 11	8	32	

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued. 1/

Test	Symbol	Conditions $-55^{\circ}C \le T_C \le +125^{\circ}C$ Unless otherwise specified	Group A subgroups	Limits		Unit
				Min	Max	
Propagation delay time, A, B, C to $\overline{Y}$	tPLH2	V_{CC} = 4.5 V to 5.5 V C_L = 50 pF ±10% R_L = 500 Ω ±5% 5/ See figure 4	9, 10, 11	7	30.5	ns
	tPHL2		9, 10, 11	7	23	
Propagation delay time, any D to Y	tPLH3		9, 10, 11	3	11	ns
	tPHL3		9, 10, 11	5	21	
Propagation delay time, any D to $\overline{Y}$	tPLH4		9, 10, 11	3	18.5	ns
	tPHL4		9, 10, 11	4	15	
Propagation delay time, $\overline{G}$ to Y	tPLH5		9, 10, 11	4	18	ns
	tPHL5		9, 10, 11	4	21	
Propagation delay time, $\overline{G}$ to $\overline{Y}$	tPLH6		9, 10, 11	5	22	ns
	tPHL6		9, 10, 11	5	25	

1/ Unused inputs that do not directly control the pin under test must be ≥ 2.5 V or ≤ 0.4 V. Unused inputs shall not exceed 5.5 V or go less than 0.0 V. No inputs shall be floated.

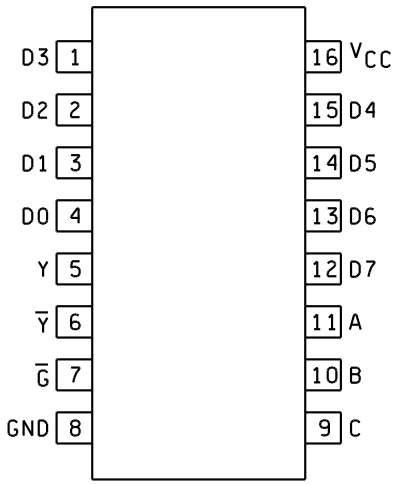
2/ All outputs must be tested. In the case where only one input at V_{IL} maximum or V_{IH} minimum produces the proper output state, the test must be performed with each input being selected as the V_{IL} maximum or V_{IH} minimum input.

3/ The output conditions have been chosen to produce a current that closely approximates one-half of the true short circuit output current, I_{OS}. Not more than one output will be tested at a time and the duration of the test condition shall not exceed 1 second.

4/ Functional tests shall be conducted at input test conditions of $GN_D \le V_{IL} \le V_{OL}$ and $V_{OH} \le V_{IH} \le V_{CC}$.

5/ The propagation delay llimits are based on single output switching. Unused inputs = 3.5 V or ≤ 0.3 V.

CASE E AND F



CASE 2

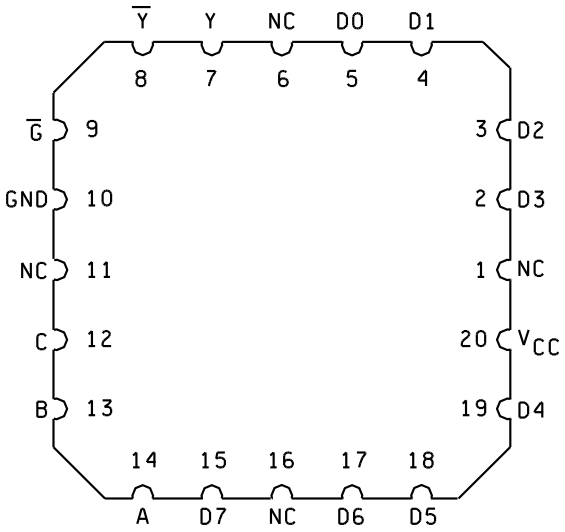


FIGURE 1. Terminal connections (top view).

INPUTS				OUTPUTS	
SELECT			STROBE		
C	B	A	$\overline{G}$	Y	$\overline{Y}$
X	X	X	H	L	H
L	L	L	L	D0	$\overline{D0}$
L	L	H	L	D1	$\overline{D1}$
L	H	L	L	D2	$\overline{D2}$
L	H	H	L	D3	$\overline{D3}$
H	L	L	L	D4	$\overline{D4}$
H	L	H	L	D5	$\overline{D5}$
H	H	L	L	D6	$\overline{D6}$
H	H	H	L	D7	$\overline{D7}$

H = high level, L = low level, X = irrelevant
D0 - D7 = the level of the D respective input

FIGURE 2. Truth table.

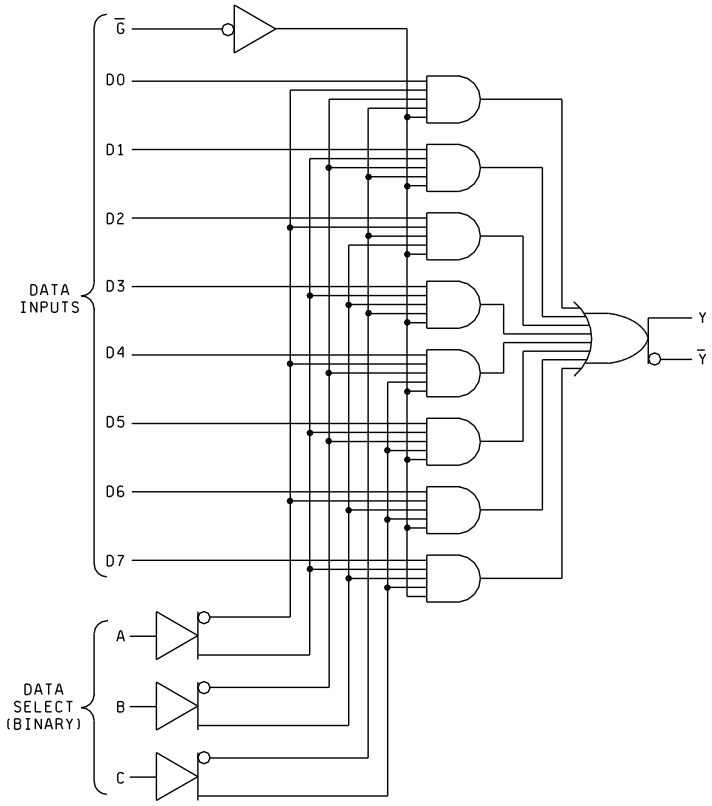
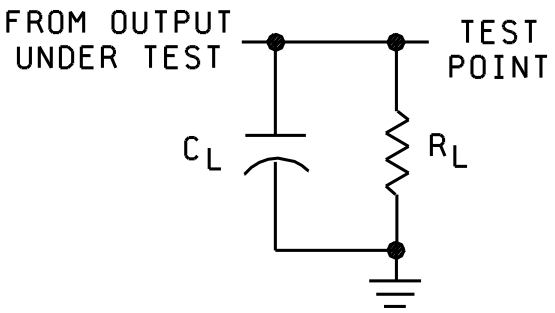
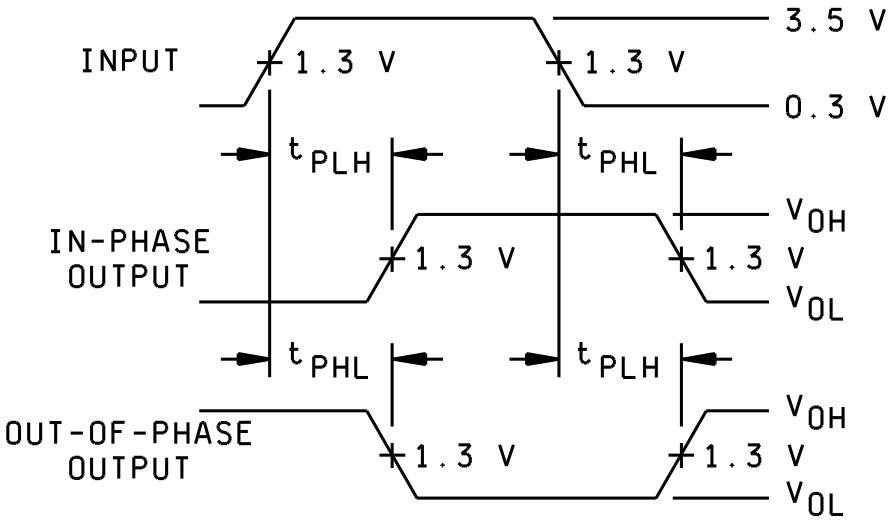


FIGURE 3. Logic diagram.



LOAD CIRCUIT FOR
BI-STATE
TOTEM-POLE OUTPUTS



NOTES:
1. C_L includes probe and jig capacitance.
2. All input pulses have the following characteristics: PRR ≤ 10 Mhz, duty cycle = 50%, $t_r = t_f = 3$ ns ±1 ns.
3. The outputs are measured one at a time with one input transition per measurement.

FIGURE 4. Switching waveforms and test circuit.

3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) T_A = +125°C, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 4, 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroup 7 functional testing shall include verification of the truth table on figure 3.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test conditions, method 1005 of MIL-STD-883.

(1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) T_A = +125°C, minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number 1/
8414101EX	01295 27014	SNJ54ALS151J 54ALS151J/883
8414101FX	01295	SNJ54ALS151W
84141012X	01295 27014	SNJ54ALS151FK 54ALS151E/883

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number	Vendor name and address
01295	Texas Instruments Incorporated P. O. Box 6448 Midland, TX 79701
27014	National Semiconductor Corporation 2900 Semiconductor Drive Santa Clara, CA 95051